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APPLICATION NO. FILING DATE		ILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO	
09/895,025	09/895,025 07/02/2001		Toshiaki Shinohara	210096US2 7453		
22850	7590	0 07/08/2004		EXAMINER		
OBLON, S	PIVAK,	MCCLELLAND, N	VU, QUANG D			
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DATE MAILED: 07/08/2004

Please find below and/or attached an Office communication concerning this application or proceeding.

		Applicatio	n No.	Applicant(s)				
		09/895,02	5	SHINOHARA, TOSHIAKI				
Office Action Summary		Examiner		Art Unit				
		Quang D V	u	2811	pr			
Period fo	The MAILING DATE of this communicate	ation appears on the	cover sheet with the c	orrespondence add	dress			
A SHOTHE I  - Exter after  - If the  - If NO  - Failu Any	ORTENED STATUTORY PERIOD FOR MAILING DATE OF THIS COMMUNIC, usions of time may be available under the provisions of SIX (6) MONTHS from the mailing date of this commun period for reply specified above is less than thirty (30) period for reply is specified above, the maximum stature to reply within the set or extended period for reply with eply received by the Office later than three months after a patent term adjustment. See 37 CFR 1.704(b).	ATION. 37 CFR 1.136(a). In no ever lication. days, a reply within the statu tory period will apply and will II. by statute, cause the appli	nt, however, may a reply be tim tory minimum of thirty (30) day expire SIX (6) MONTHS from cation to become ABANDONE	nely filed s will be considered timely the mailing date of this co D (35 U.S.C. § 133).	′. ∘mmunication.			
Status								
1)⊠	Responsive to communication(s) filed	on <u>20 April 2004</u> .						
2a)⊠	This action is <b>FINAL</b> . 2b	) This action is no	on-final.					
3)□	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.							
Dispositi	on of Claims							
5)⊠ 6)⊠ 7)□	Claim(s) 1-11 is/are pending in the ap 4a) Of the above claim(s) is/are Claim(s) 6-10 is/are allowed. Claim(s) 1-5 and 11 is/are rejected. Claim(s) is/are objected to. Claim(s) are subject to restriction	withdrawn from cor						
Applicat	ion Papers							
10)	The specification is objected to by the The drawing(s) filed on is/are: a Applicant may not request that any objection Replacement drawing sheet(s) including the oath or declaration is objected to be	a) accepted or b)[ ion to the drawing(s) b he correction is require	e held in abeyance. Seed if the drawing(s) is ob	e 37 CFR 1.85(a). jected to. See 37 CF				
Priority (	ınder 35 U.S.C. § 119							
12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).  a) All b) Some * c) None of:  1. Certified copies of the priority documents have been received.  2. Certified copies of the priority documents have been received in Application No  3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).  * See the attached detailed Office action for a list of the certified copies not received.								
2) Notice 3) Infor	et(s)  ce of References Cited (PTO-892)  ce of Draftsperson's Patent Drawing Review (PTo- mation Disclosure Statement(s) (PTO-1449 or Port No(s)/Mail Date		4) Interview Summary Paper No(s)/Mail D 5) Notice of Informal F 6) Other:		)-152)			

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#### **DETAILED ACTION**

### Claim Rejections - 35 USC § 102

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

2. Claims 1, 3, 4, 5 and 11 are rejected under 35 U.S.C. 102(b) as being anticipated by US Patent No. 5,291,065 to Arai et al.

Regarding claim 1, Arai et al. (figure 10) teach a semiconductor device comprising: a semiconductor element (5);

a metal block (330) having a first surface and a second surface opposite to the first surface;

an aluminum wire (5g) having an electrode terminal joined to the first surface of the metal block (330); and

a ceramic substrate (301) having metal layers (312, 340) formed on both surfaces, one of the metal layers (312) joined directly by a first jointing material (material layer [320]) to the second surface of the metal block (330).

It is inherent that the semiconductor element (5) having an electrode for the I/O connection.

It is inherent that the semiconductor element (5) and the electrode are joined to the first surface of the metal block (330) through a second jointing material (a material layer is under the

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semiconductor element [5]) for the interconnection between the semiconductor element and the external device.

Regarding claim 3, Arai et al. teach the semiconductor element includes a plurality of semiconductor elements (5);

the metal block (330) and the ceramic substrate (301) are separated per insulation unit of at least one of the plurality of semiconductor elements (5);

the metal block (330) is provided to be in correspondence with at least one of the plurality of semiconductor elements (5); and

the ceramic substrate (301) extends over all of the plurality of semiconductor elements (5) for forming the insulation unit.

Regarding claim 4, Arai et al. inherently teach the metal block (330) includes a surface having a region larger than that of the second jointing material, which is in contact with the metal block.

Regarding claim 5, Arai et al. teach a gap between the metal block (330) and the semiconductor element (5) becomes wider as a distance from a center of the semiconductor element (5) becomes longer; and the gap is filled with the second jointing material (a material layer is under the semiconductor element [5]).

Regarding claim 11, Arai et al. teach the semiconductor element includes a plurality of semiconductor elements (5);

the metal block (330) and the ceramic substrate (301) are separated per insulation unit of at least one of the plurality of semiconductor elements (5);

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the ceramic substrate (301) is provided to be in correspondence with at least one of the plurality of semiconductor elements (5); and

the metal block (303) extends over all of the plurality of semiconductor elements (5) for forming the insulation unit.

# Claim Rejections - 35 USC § 103

- 3. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
  - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 4. Claim 2 is rejected under 35 U.S.C. 103(a) as being unpatentable over US Patent No. 5,291,065 to Arai et al.

Regarding claim 2, Arai et al. differ from the claimed invention by not showing the metal layers formed on the both surfaces of the ceramic substrate are the same with each other in thickness. It would have been obvious to one having ordinary skill in the art at the time the invention was made for the metal layers formed on the both surfaces of the ceramic substrate are the same with each other in thickness because it depends on the amount of heat that dissipated by the integrated circuit.

#### Allowable Subject Matter

5. Claims 6-10 are allowed.

## Response to Arguments

Applicant's arguments filed 04/20/04 have been fully considered but they are not persuasive.

It is argued, in page 7 of the remarks, that Arai et al. do not teach or suggest a ceramic substrate having metal layers formed on both surfaces, one of the metal layers joined directly by a first jointing material to the second surface of the metal block. This argument is not convincing because Arai et al. (figure 10) teach a ceramic substrate (301) having metal layers (312, 340) formed on both surfaces, one of the metal layers (312) joined directly by a first jointing material (material layer [320]) to the second surface of the metal block (330). Applicant does not show what is the material of the jointing material. Therefore, the material layer (320) can be read on the jointing material.

### Conclusion

THIS ACTION IS MADE FINAL. Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event,

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however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Quang D Vu whose telephone number is 571-272-1667. The examiner can normally be reached on Monday-Friday.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Eddie Lee can be reached on 571-272-1732. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

qv June 30, 2004 Vanghambee Kang Donghee Kang Primary Gramina A-U. 2811